

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED


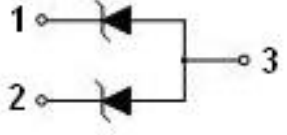
AZ23C2V7-AZ23C39

Product specification

FEATURES

- Dual zeners in common anode configuration.
- 300mW power dissipation rating.
- Ideally suited for automatic insertion.
- ΔV_z for both diodes in one case is $\leq 5\%$.
- Common cathode style available see DZ series.
- Also available in lead free version

Reference News

PACKAGE OUTLINE	PIN CONFIGURATION
	
SOT-23	

Maximum Ratings(Ta=25 °C unless otherwise specified)

Characteristic	Symbol	Value	Unit
Forward Voltage @ $I_F = 10\text{mA}$	V_F	0.9	V
Power Dissipation	P_D	300	mW
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	417	°C/W
Operation Junction and Storage Temperature Range	T_J, T_{STG}	-55~+150	°C

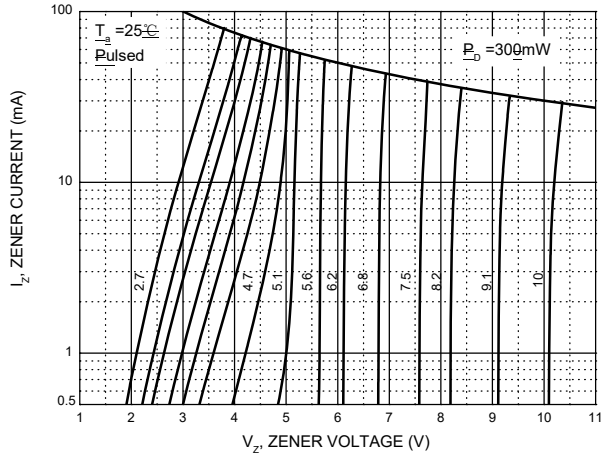
ELECTRICAL CHARACTERISTICS

T_a=25℃ unless otherwise specified

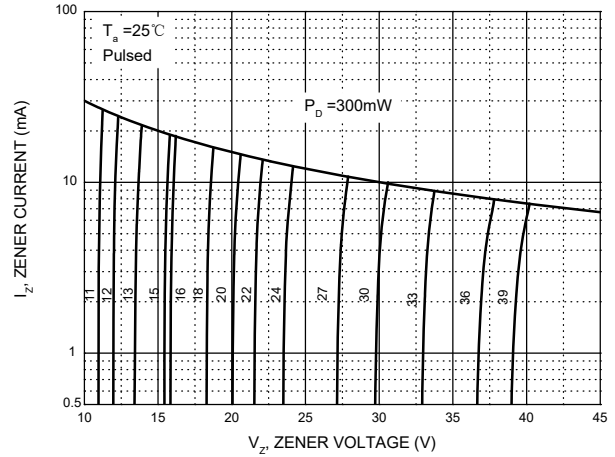
Type Number	Marking Code	Zener Voltage Range (note1)	Maximum Zener Impedance (note 2)		Typical Temperature Coefficient	Min Reverse Voltage (note1)
		@ I _{ZT} =5.0mA	Z _{ZT} @I _{ZT} =5.0mA	Z _{Zk} @I _{Zk} =1.0mA		@I _R =0.1 μA
		V _Z (V)	Ω	Ω		V _R (V)
AZ23C2V7	KD1	2.5-2.9	83	500	-0.065	—
AZ23C3V0	KD2	2.8-3.2	95	500	-0.060	—
AZ23C3V3	KD3	3.1-3.5	95	500	-0.055	—
AZ23C3V6	KD4	3.4-3.8	95	500	-0.055	—
AZ23C3V9	KD5	3.7-4.1	95	500	-0.050	—
AZ23C4V3	KD6	4.0-4.6	95	500	-0.035	—
AZ23C4V7	KD7	4.4-5.0	78	500	-0.015	—
AZ23C5V1	KD8	4.8-5.4	60	480	+0.005	0.8
AZ23C5V6	KD9	5.2-6.0	40	400	+0.020	1.0
AZ23C6V2	KDA	5.8-6.6	10	200	+0.030	2.0
AZ23C6V8	KDB	6.4-7.2	8.0	150	+0.045	3.0
AZ23C7V5	KDC	7.0-7.9	7.0	50	+0.050	5.0
AZ23C8V2	KDD	7.7-8.7	7.0	50	+0.055	6.0
AZ23C9V1	KDE	8.5-9.6	10	50	+0.065	7.0
AZ23C10	KDF	9.4-10.6	15	70	+0.065	7.5
AZ23C11	KDG	10.4-11.6	20	70	+0.070	8.5
AZ23C12	KDH	11.4-12.7	20	90	+0.075	9.0
AZ23C13	KDI	12.4-14.1	25	110	+0.080	10.0
AZ23C15	KDJ	13.8-15.6	30	110	+0.080	11.0
AZ23C16	KDK	15.3-17.1	40	170	+0.090	12.0
AZ23C18	KDL	16.8-19.1	50	170	+0.090	14.0
AZ23C20	KDM	18.8-21.2	50	220	+0.090	15.0
AZ23C22	KDN	20.8-23.3	55	220	+0.090	17.0
AZ23C24	KDO	22.8-25.6	80	220	+0.090	18.0
AZ23C27	KDP	25.1-28.9	80	250	+0.090	20.0
AZ23C30	KDQ	28-32	80	250	+0.090	22.5
AZ23C33	KDR	31-35	80	250	+0.090	25.0
AZ23C36	KDS	34-38	90	250	+0.090	27.0
AZ23C39	KDT	37-41	90	300	+0.110	29.0

Notes: 1. Short duration test pulse used to minimize self-heating effect.
2. f=1kHz

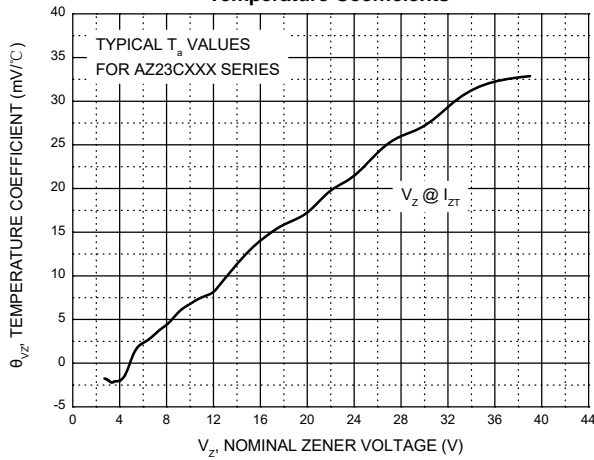
Zener Characteristics (V_Z Up to 10 V)



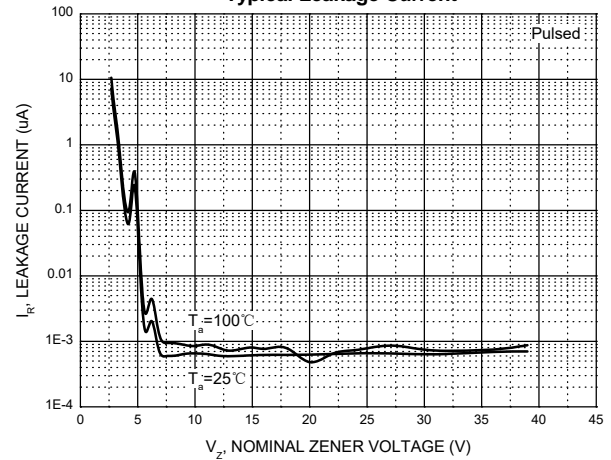
Zener Characteristics (11 V to 39 V)



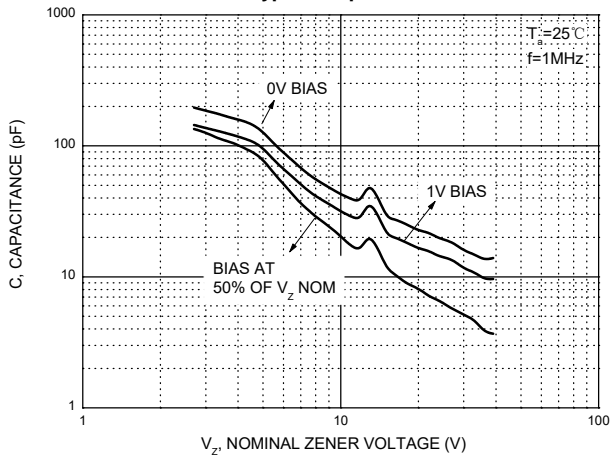
Temperature Coefficients



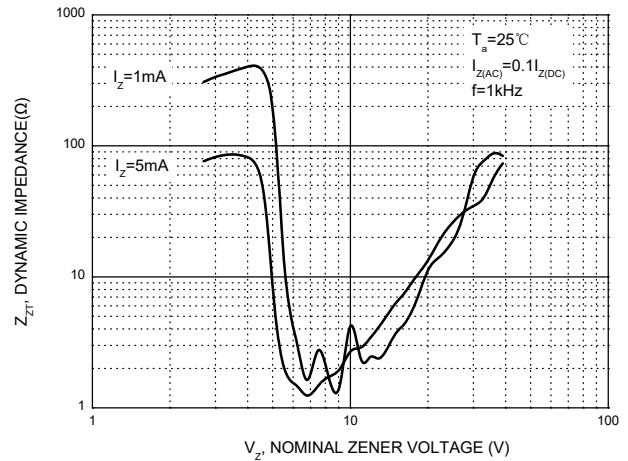
Typical Leakage Current



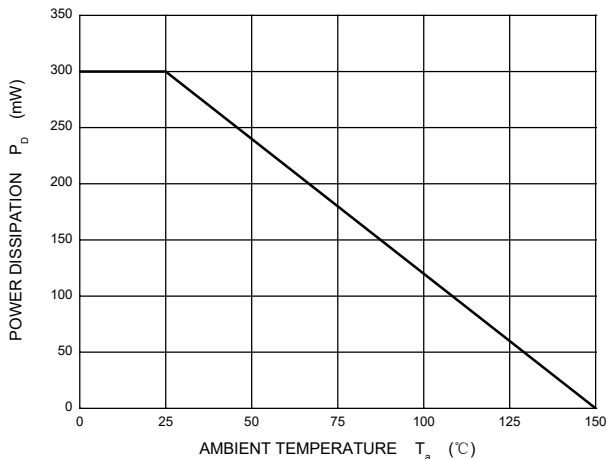
Typical Capacitance



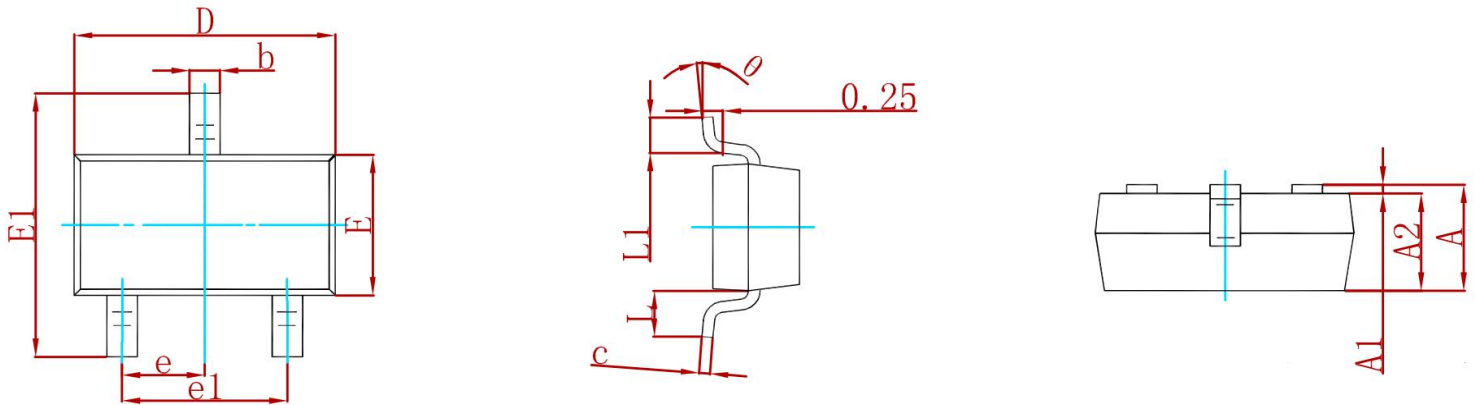
Effect of Zener Voltage on Zener Impedance



Power Derating Curve

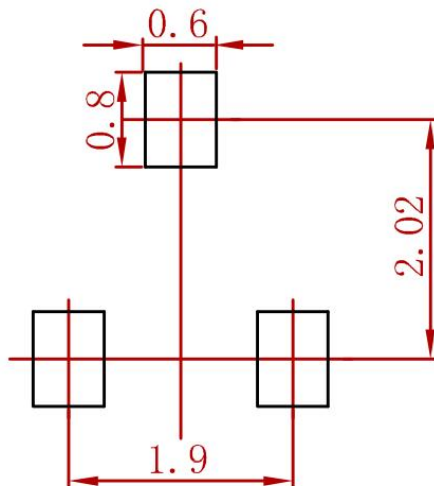


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: $\pm 0.05\text{mm}$.
3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
AZ23C2V7-AZ23C39	SOT-23	3000

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